

Connor Solutions Ltd - Capabilities

CAPABILITY/TECHNOLOGY	EQUIPMENT - MAKE AND MODEL	COMPONENTS PER HOUR (CPH)	PANEL DIMENSIONS	COMPONENT SPEC
SURFACE MOUNT ASSEMBLY				
Automatic Board Loader	JOT, Nutek, Cooper Rason			
Screen Printer	DEK 265 GS (X2) and DEK Horizon - Capable of printing glue			
High Speed Placement	Fuji NXT, 2 lines of 4xM3, 2xM6 and 1 line of 4xM3, 4xM6 modules with changeable head configurations	H12 Head - 14K, H08 Head - 10K/9.4K, H04 Head - 6K/5.6K, H01 Head - 3.5K/3.2K	Min - 50mm (L) X 50mm (W) Max - 543mm (L) X 610mm (W)	Min - 0402 (14115) 0603 (0201) Max - 74 X 74 (32 X 180) Max Comp. Height - 25.4mm
Fine Pitch Placement	Fuji NXT, 2 lines of 4xM3, 2xM6 and 1 line of 4xM3, 4xM6 modules with changeable head configurations			
Reflow Oven - number of zones	Vitronics Magnatherm - 8 heat plus 2 cool			
	Soltec Quantis - 6 heat plus 2 cool			
	BTU VIP 98 - 7 heat plus 2 cool			
Inspection	Mantis x10 scopes, Lynx System x40 digital scopes (x3), X-ray and Ersascope inspection			
AOI	Cyberoptics KS100 (x3)			

THRU-HOLE ASSEMBLY				
Automatic Axial Insertion	Universal S/H VCD - 6287A	15,000	Max - 450mm (L) X 400mm (W)	Min - 0.400" (10mm) pitch Max - 0.800 (20mm) pitch (Body size dependant)
	Universal D/H VCD - 6292A	32,000	Max - 450mm (L) X 400mm (W)	
Automatic Radial Insertion	Universal Radial 5 - 6368D	21,000	Max - 450mm (L) X 400mm (W)	5.0mm and 7.5mm pitch devices
	Universal Radial 8 - 6380A	16,000	Max - 450mm (L) X 400mm (W)	
Automatic DIP Insertion	Universal DIP Inserter - 6778A	4,500	Max - 450mm (L) X 400mm (W)	Min - 8 pin Max - 32 pin (0.300"(7.5mm)) pitch
Automatic Tag Insertion	Autosplice	4,000	Max - 450mm (L) X 400mm (W)	
	Harwin - 718	4,000	Max - 450mm (L) X 400mm (W)	
Semi-Automatic Tag Insertion				
Component Preparation				
Automatic Cut and Preform	Various axial, radial, dip component cut and preform tools and equipment			
Manual Cut and Preform	Customer specific tooling and presses			
Wire Cut and Strip				
Semi Automatic IC Programming	Dataman 48XP	Device Specific		
Automatic Pin Extraction (Molex)				
Flowline Assembly (manual placement)	3 lines of 5 pre-wave and 8 post-wave operators			
Lead Free Wave Solder Machine	Nousstar NS-TW-350 LFS, NS-TW-350 LFI		400mm (L) X 250mm (W) (If using standard carrier - bespoke solutions can be applied)	
Tin/Lead Wave Solder Machine	Nousstar NS-TW-350 LFS			
Selective Solder Machine	TOP 375 - Pb Free Mini Wave, TOP 353 Tin/Lead Mini Wave			
Automatic/Semi Automatic Depanel	Maestro 4M			
Semi Automatic Rivet Insertion	Avdel Electronic Hydra and Footpedal			

FINAL ASSEMBLY - BOX BUILD				
Product Housing/Encapsulation	Manually applied and robotically applied conformal coat capability. Also in house ability to encapsulate in resin.			
Cable Harness Assembly	Some limited in-house capability. Mainly outsourced.			
Full Box Build	Progressive assembly and cellular layouts			

TEST				
ICT	Teradyne Z1880 (x2) Z1885	Up to 2000 node - board dependant		
	HP3070			
Flying Probe	Seica S40 Pilot LX	Board dependant		
Full Functional Test Capability	National Instruments PXI LabVIEW platform multiple card based measurements available. Standard scopes, sig gen. Power supplies available.			
Other	Checksum (x3) Tester			

OTHER REQUIREMENTS				
Rework/Repair	Hakko Hot Air Repair Systems			
	PDR X410Vi focussed Infra Red rework system (BGA etc)			
Laser Etch	LET automation combi cell label/laser			
Label Printing - Zebra etc	Z4M Plus, Z6M (x2), Z4M (x6)			
Stores Kitting	Pick to work order. Low value items held lineside. Three vendor managed consigned inventory programmes.			
MRP/ERP system	Growthpower			
Product Traceability	Paper based at the moment. Currently evaluating MES system. Facility AS9100 approved.			
Packing	As required. Storage and logistics capability.			